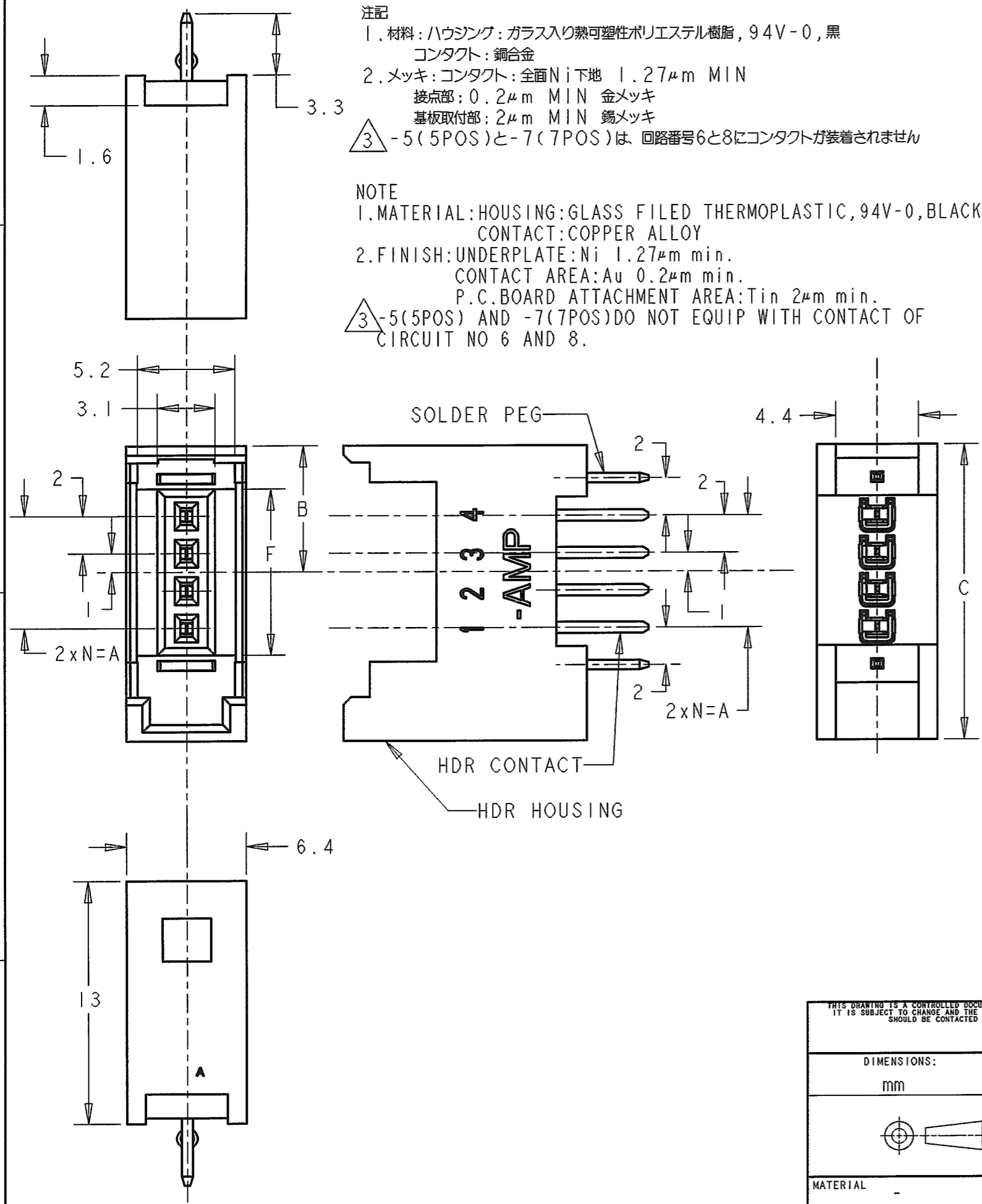
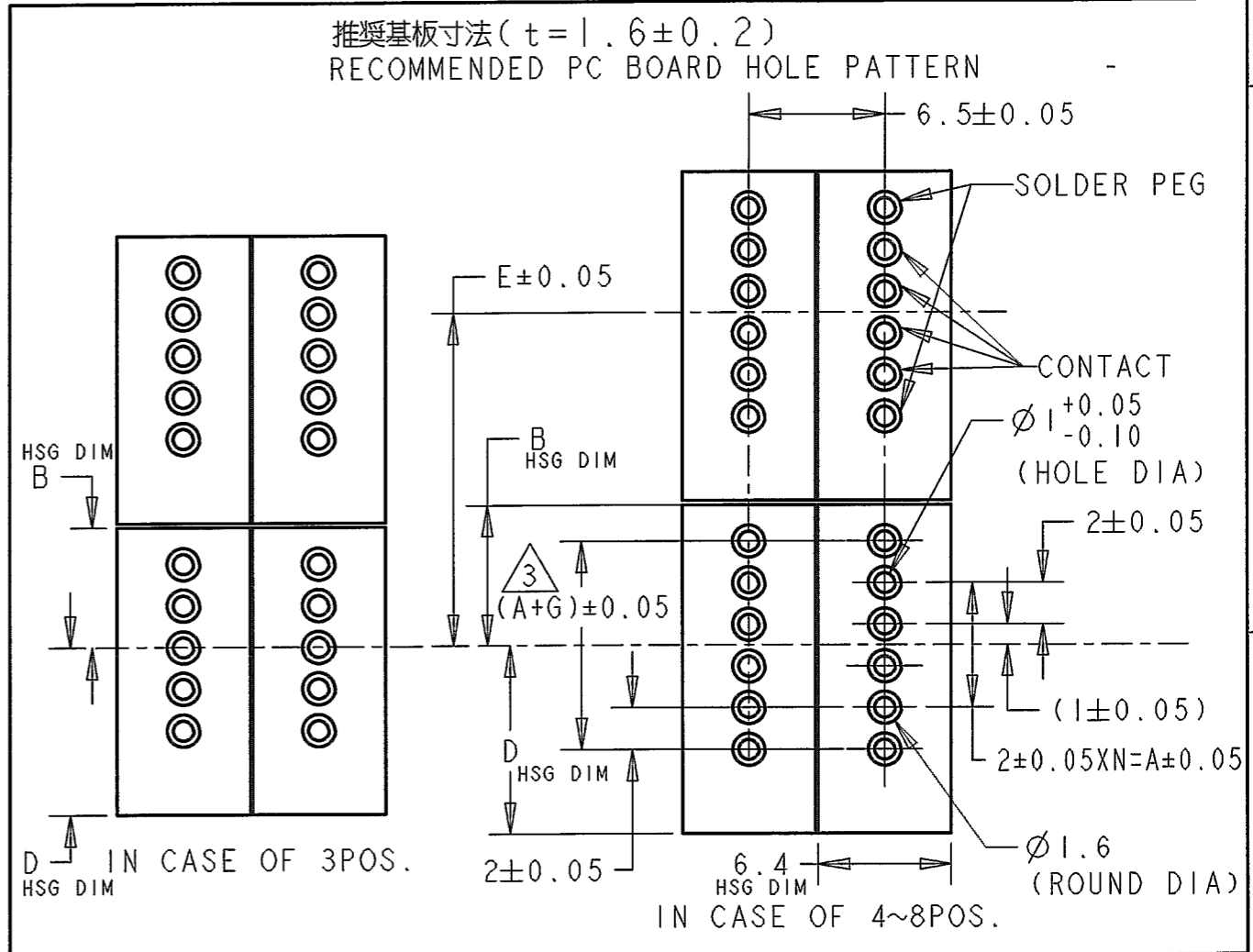


LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
J	-	0		RELEASED FJ00-1726-01	10SEP2001	D.M	S.M
		A		ADD P/N FJ00-1227-02	10MAY2002	D.M	S.M
		AI		REVISED FJ00-2030-02	27SEP2002	D.M	S.M
		B		REVISED FJ00-0125-03	24FEB04	K.R	K.S

注記
 1. 材料:ハウジング:ガラス入り熱可塑性ポリエステル樹脂, 94V-0, 黒
 コンタクト:銅合金
 2. メッキ:コンタクト:全面Ni下地 1.27μm MIN
 接点部:0.2μm MIN 金メッキ
 基板取付部:2μm MIN 錫メッキ
 △3 -5(5POS)と-7(7POS)は、回路番号6と8にコンタクトが装着されません

NOTE
 1. MATERIAL:HOUSING:GLASS FILED THERMOPLASTIC, 94V-0, BLACK
 CONTACT:COPPER ALLOY
 2. FINISH:UNDERPLATE:Ni 1.27μm min.
 CONTACT AREA:Au 0.2μm min.
 P.C. BOARD ATTACHMENT AREA:Tin 2μm min.
 △3 -5(5POS) AND -7(7POS) DO NOT EQUIP WITH CONTACT OF
 CIRCUIT NO 6 AND 8.



△3	4	16.9	24	13.05	23.8	10.75	14	7	8	1473565-8
△3	6	16.9	24	13.05	23.8	10.75	12	7	7	1473565-7
△3	4	12.9	20	11.05	19.8	8.75	10	5	6	1473565-6
△3	6	12.9	20	11.05	19.8	8.75	8	5	5	1473565-5
△3	4	8.9	16	9.05	15.8	6.75	6	3	4	1473565-4
△3	4	6.9	14	8.05	13.8	5.75	4	2	3	1473565-3
	G	F	E	D	C	B	A	N	POS	P/N

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION
 IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION
 SHOULD BE CONTACTED FOR THE LATEST REVISION.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± ±0.2 1 PLC ± ±0.2 2 PLC ± ±3° 3 PLC ± ±3° 4 PLC ± ± ANGLES ± ±	DWN D. MITSUGI 10SEP2001 CHK S. MANABE 10SEP2001 APVD S. MANABE 10SEP2001 PRODUCT SPEC 108-5765 APPLICATION SPEC - WEIGHT -	tyco Electronics Tyco Electronics AMP K.K. Kawasaki, Japan
MATERIAL -	FINISH -	NAME HDR-ASSY (IROW) FOR E-CON - RITS CONN. -	RESTRICTED TO -
CUSTOMER DRAWING		SIZE A3 CAGE CODE 00779 DRAWING NO C=1473565	SCALE 4:1 SHEET 1 OF 1 REV B